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Aalto University

Copper and its chemistry

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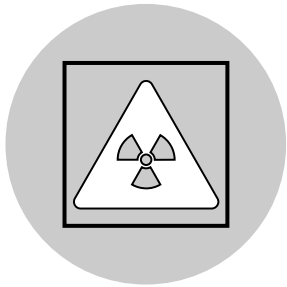
Marechal Sonia

Weppe Kelly

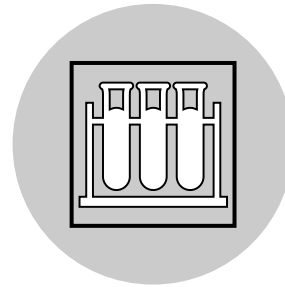
School of Chemical Engineering

Aalto University

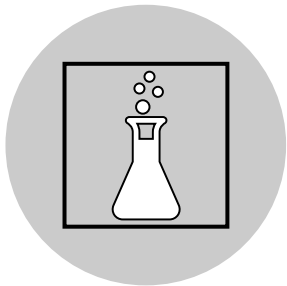
Overview



Element



Chemistry



Compounds



Applications



Element

Origin - Abundancy - Properties -
Production

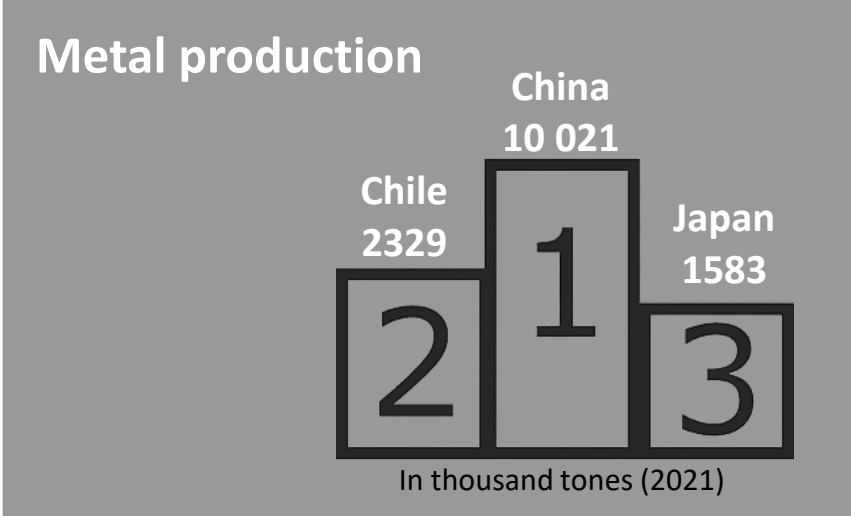
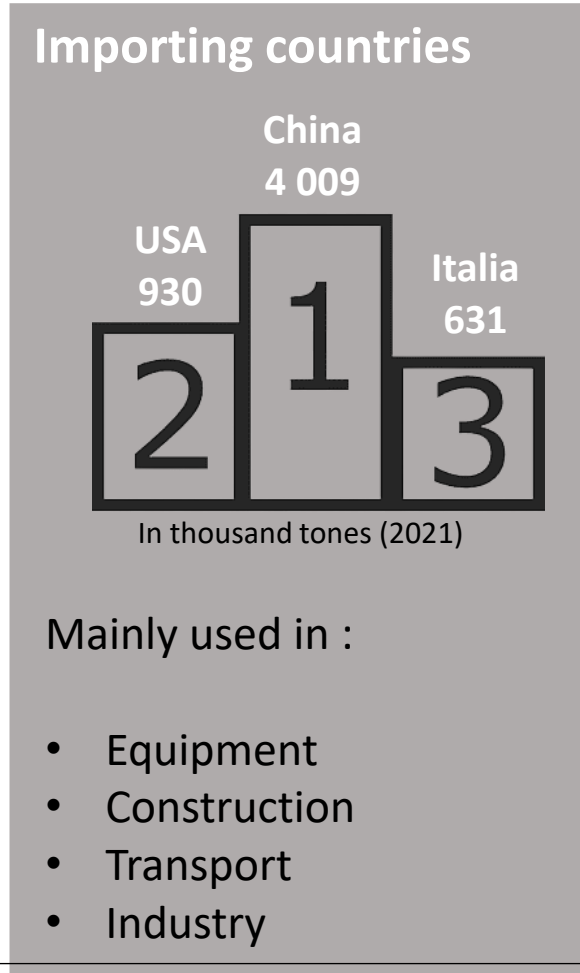
Presentation

- The oldest traces :
 - first half of the 5th millennium BC ,
 - 6 000 years ago : copper ores mining
- Name comes from the Latin cyprum (island of Cyprus)
- 26th most abundant element in the earth's crust (50 ppm)
- Properties :
 - Reddish color
 - very good thermal and electrical conductivity
 - resistant to atmospheric and marine corrosion
 - very malleable, tough and ductile and relatively soft
- Copper ores come in two main chemical forms :
 - Sulphide: CuFeS_2 , Cu_5FeS_4 , Cu_2S --> 80% of world production
 - Oxidised : CuCO_3 , $\text{Cu}(\text{OH})_2$, 2CuCO_3 , $\text{Cu}(\text{OH})_2$, Cu_2O



- The element copper, from the ores, is obtained by two metallurgical methods :
 - Pyrometallurgy (sulphide ores)
 - $\text{Cu}_2\text{O} + \text{FeS} = \text{Cu}_2\text{S} + \text{FeO}$
 - $\text{Cu}_2\text{S} + 3/2 \text{O}_2 = \text{Cu}_2\text{O} + \text{SO}_2$
 - $2 \text{Cu}_2\text{O} + \text{Cu}_2\text{S} = 6 \text{Cu} + \text{SO}_2$
 - Hydrometallurgy (oxidised or poor sulphide ores)
 - A dissolution
 - Solvent extraction
 - Electrolysis

Export and import

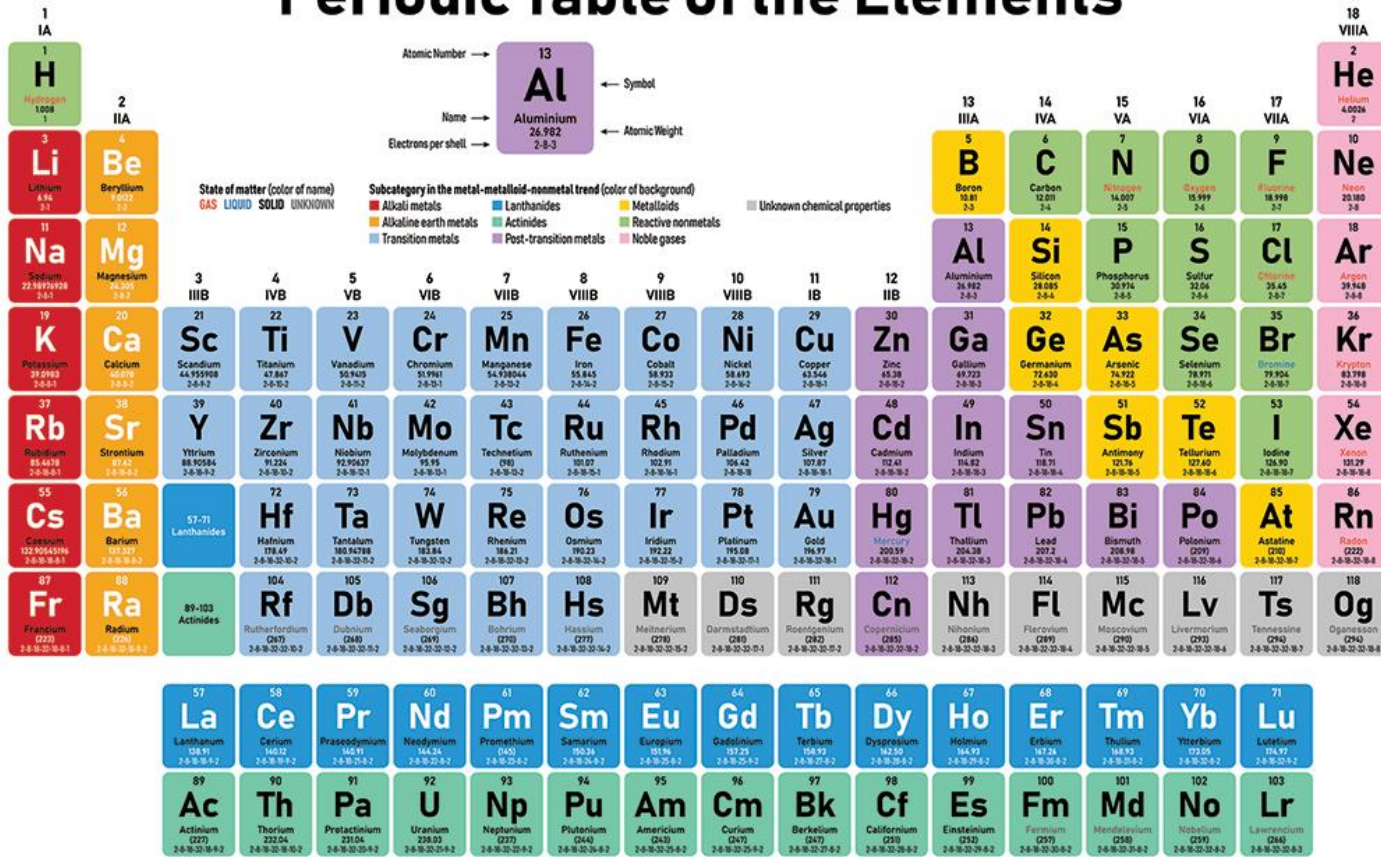


Chemistry

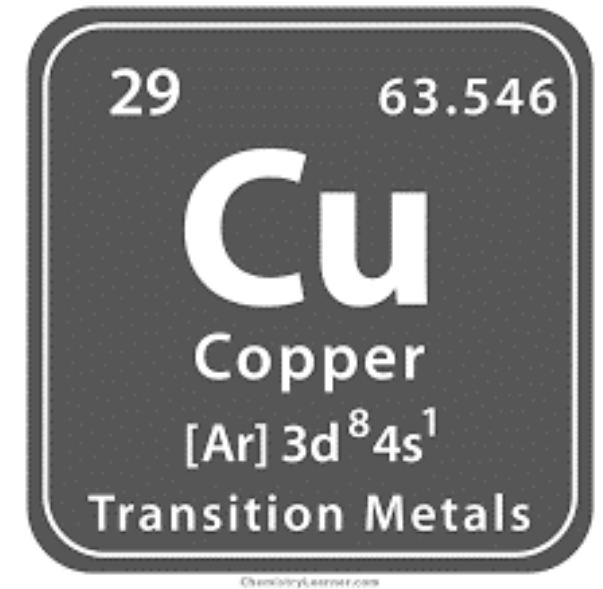
Electronic configuration – Oxidation
state - Reactivity

Chemistry

Periodic Table of the Elements



Electronic configuration



Exception to the Klechkowski's rule

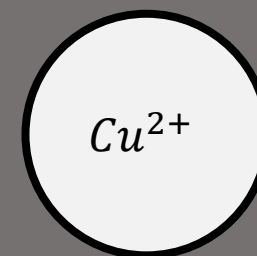
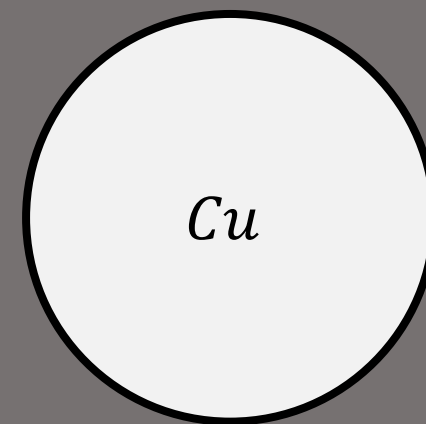
Chemistry

Oxidation states

- Most common oxidation state **+2** (CuCl_2 , CuO , CuSO_4), less common **+1** (CuCl , Cu_2S , Cu_2O),
- Can have oxidation state of **+3** (KCuO_2 , K_3CuF_6) and **+4** (Cs_2CuF_6),
- **Copper (I) compounds** : cuprous compounds, diamagnetic, colourless, tetrahedral or square planar geometry, more stable state in solid compounds at moderate temperatures
- **Copper (II) compounds** : cupric compounds, usually coloured, affected by Jahn Teller distortions, more stable state in aqueous solutions

Metallic and ionic sizes

- 135pm and 71-87pm



Chemistry

Reactivity

- No reaction with water
- Slowly react with atmospheric oxygen → green layer of verdigris (copper carbonate)
- Protection of the underlying metal from further corrosion = **passivation**
- In the absence of CO₂, oxidation in air begins at 120 °C
- Reacts with hydrogen sulphide to form various copper sulphides
- low reactivity + malleability = ideal for architecture



Compounds

Properties and Applications

Compounds of copper in +1 Oxidation

Cuprous oxide, (Cu₂O)

- Melting point of 1235 °C, and diamagnetic
- It is used in pigments, fungicides, in rectifier diodes before the use of silicon (due to semiconducting properties)

Cuprous chloride, (Cu₂Cl₂)

- Whitish to greyish solid, moist air converts into greenish color
- Cuprous chloride is used as catalyst in organic reactions, condensing agent for soap and fats

Cuprous sulfide, (Cu₂S)

- Occurs in the form of black powder or lumps, and melting point is 1130 °C
- Most used in industries such as luminous paints, solar cells, electrodes and solid lubricants

Compounds of copper in +2 Oxidation

Cupric oxide, (CuO)

- Appear as brownish black powder, with melting point of 1201 °C.
- Used in glass industry, porcelain glazes, and artificial gems. Also use as an oxidation catalyst.

Cupric chloride (CuCl₂)

- It is yellowish to brown powder, with 498 °C melting point.
- Use in wood preservative, dyeing and printing of fibers, pigments of glass.

Cupric sulfate (CuSO₄)

- It also exist as hydrated form CuSO₄·5H₂O and known as blue vitriol.
- For agriculture purposes, as a pesticides, germicides, soil additive, also in medicines.

Compounds of copper

Other compounds of copper

- **ON = +3**: Examples are KCuO_2
- **ON = +4**: An example is Cs_2CuF_6
- Copper acetate $\text{Cu}(\text{CH}_3\text{COO})_2$
- Copper nitrate $\text{Cu}(\text{NO}_3)_2$
- Copper oxychloride $\text{Cu}_2(\text{OH})_3\text{Cl}$
- Copper cyanide CuCN
- Copper bromide CuBr_2

Applications



Atomic Layer Deposition of Copper Metal Films

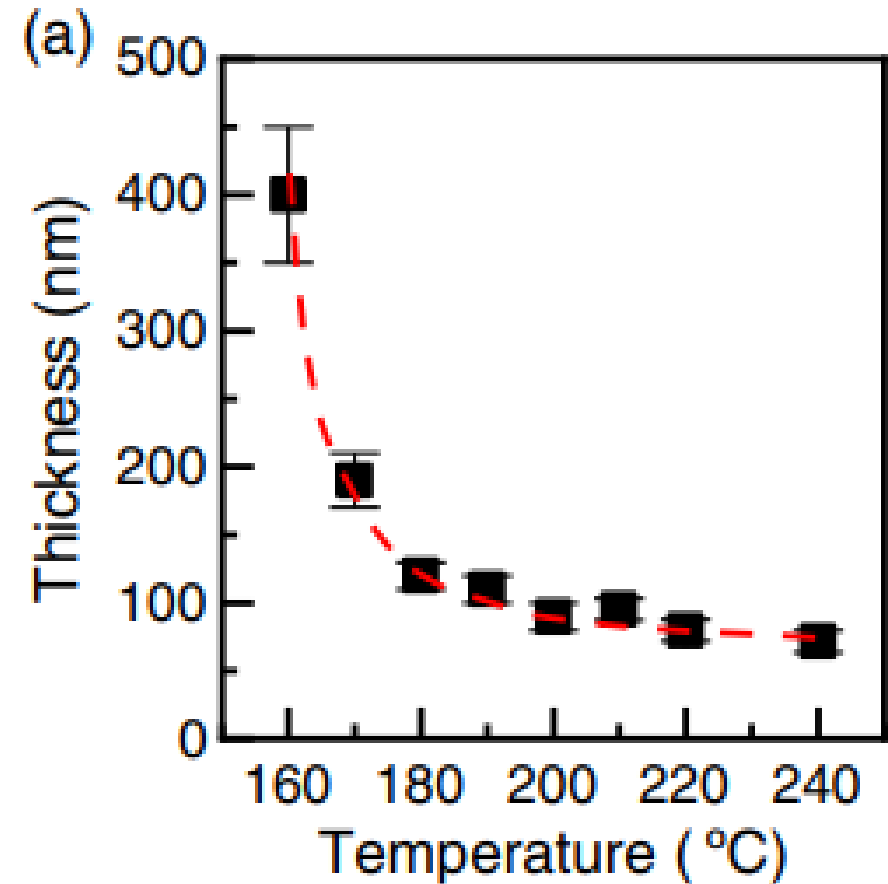
Atomic Layer Deposition of Copper Metal Films

ALD of Cu(acac)₂ and Hydroquinone Reductant

- Copper has low sensitivity and high resistance to electromigration
- The process of ALD takes place at low temperature
- Band gap of 2.0 eV
- High growth rate of 1.8 Å/cycle

Uses

- Microelectronic devices
- Integrated circuits
- Printed circuit boards



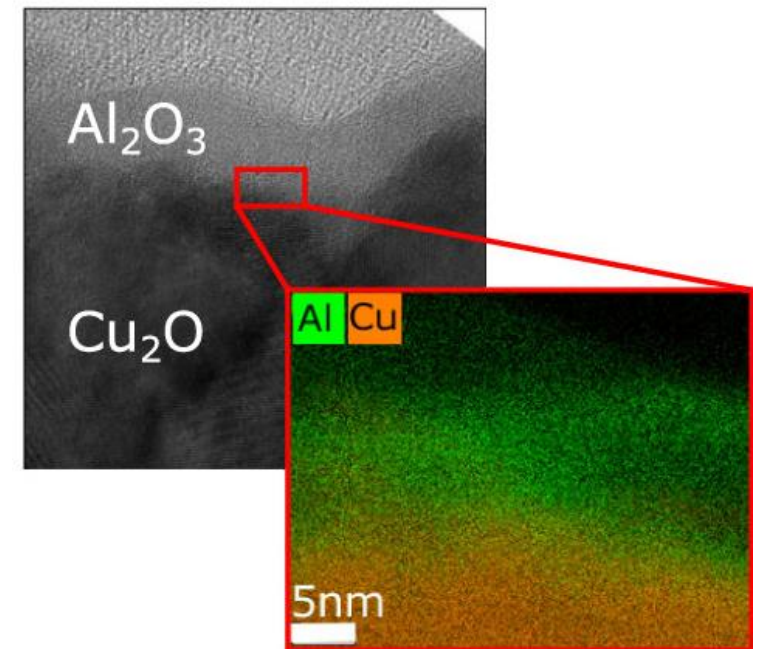
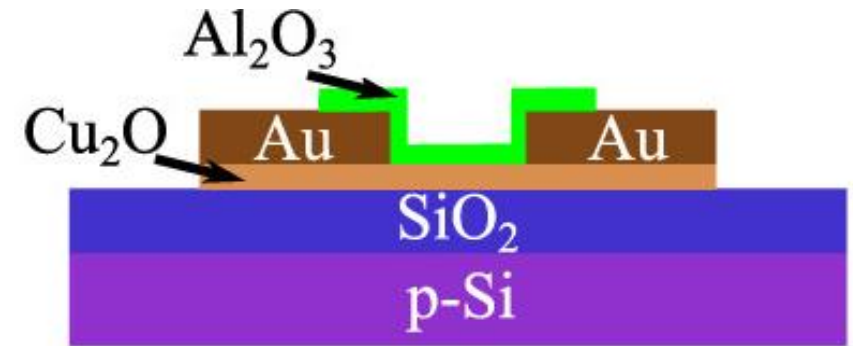
Atomic Layer Deposition of Copper Metal Films

Improvement of oxidation resistance of copper

- Al_2O_3 films were deposited by the atomic layer deposition (ALD) technique onto pure copper
- Following Improvements achieved
- Denser structure
- Hardness

Applications

- Brightness enhancement films for liquid crystal displays (LCD)
- Micro-lens arrays for antireflective polymer optical films



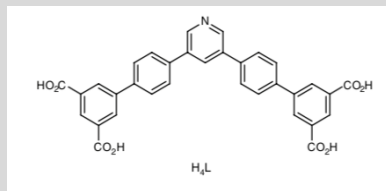
Reversible coordinative binding and separation of sulfur dioxide in a robust metal–organic framework with open copper sites

Context

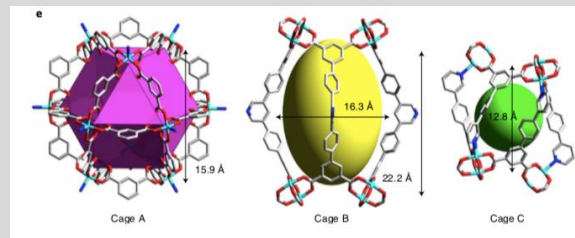
- **Challenge** : reduce SO₂ emissions (anthropogenic sources account for >87% of global emissions)

Development of dry regenerable SO₂ sorbents operating under ambient conditions

- **First idea** : Organometallic structure (MOF) sorbent but reversibility and/or limited stability in contact with highly corrosive SO₂
- **Second idea** : Organometallic structure (MOF) with Open Metal Sites (OMS) : [Cu₂(L)] (where L is H₄L = 4',4'''-(pyridine-3,5-diyl)bis([1,1'-biphenyl]-3,5- dicarboxylic acid)), named MFM-170.



Structure of H₄L (ligand)



Structure of MFM-170 from single-crystal X-ray diffraction data

- **Efficiency of OMS :**

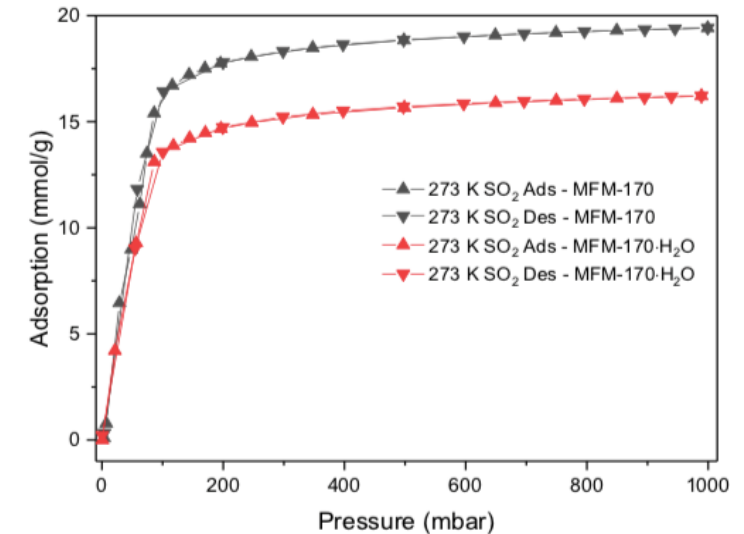


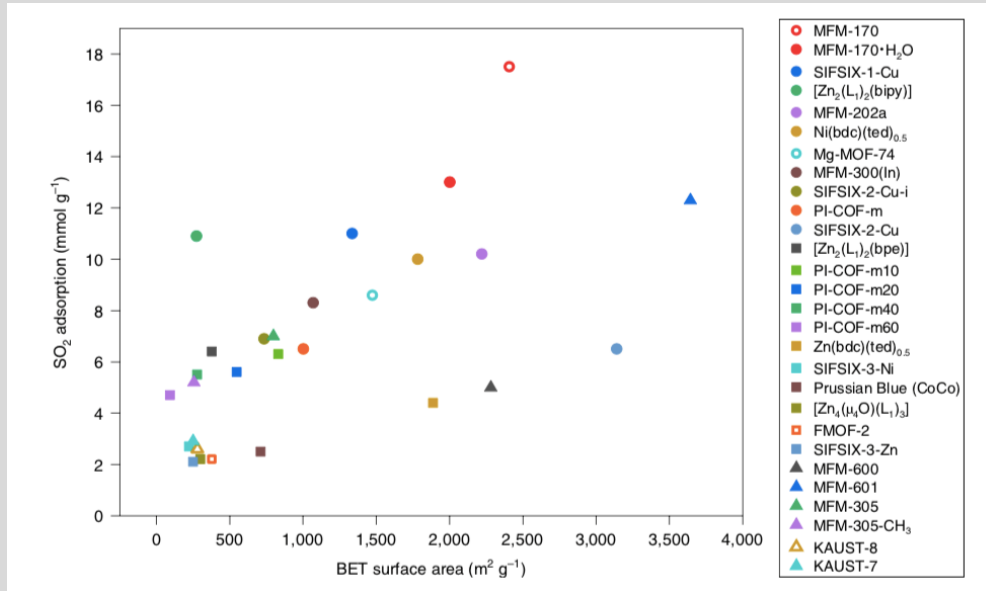
Fig. S15. Comparison of SO₂ isotherms up to 1 bar for MFM-170 (black) and MFM-170-H₂O (red) at 273 K. MFM-170-H₂O was activated by evacuation at room temperature until the mass was stable. MFM-170 was activated by heating at 423 K under vacuum until the mass was stable.

Isotherms were measured for the material saturated with MFM-170-H₂O (no OMS) and MFM-170 (with OMS)

The difference corresponds to about twice the density of open Cu(ii) sites (1.46mmolg⁻¹)

Properties

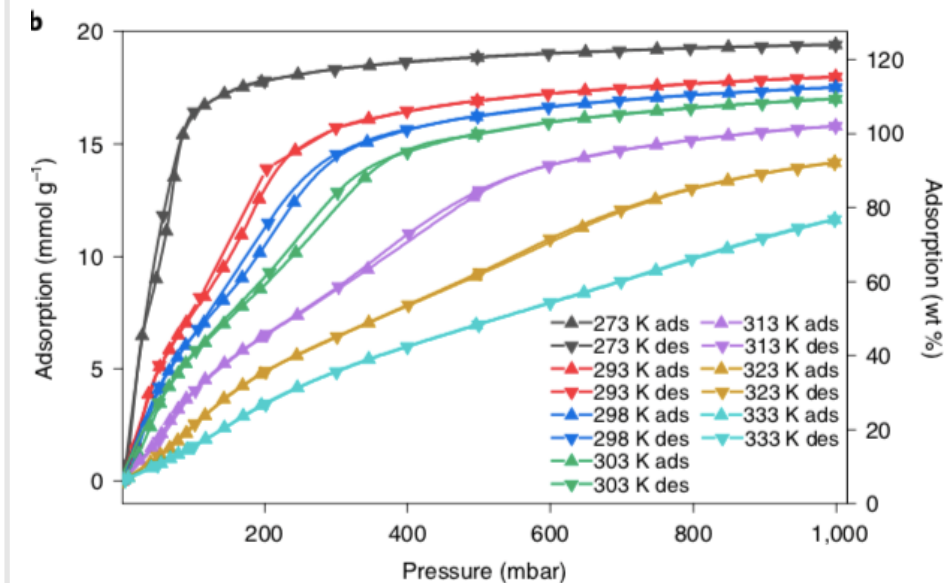
- High SO₂ adsorption



SO₂ adsorption capacity at 298 K and 1.0 bar :

- MFM-170 : 17.5 mmolg⁻¹ at 298 K and 1.0 bar
- MFM-601 : 12.3 mmolg⁻¹
- SIFSIX-1-Cu : 11.0 mmolg⁻¹
- [Zn₂(L₁)₂(bipy)] : 10.9 mmolg⁻¹ at 293

Strong SO₂ adsorption at high temperatures and at low and high pressure (11.6 mmol g⁻¹ at 333 K and 1bar) :



Properties

- **High thermal and chemical stability**

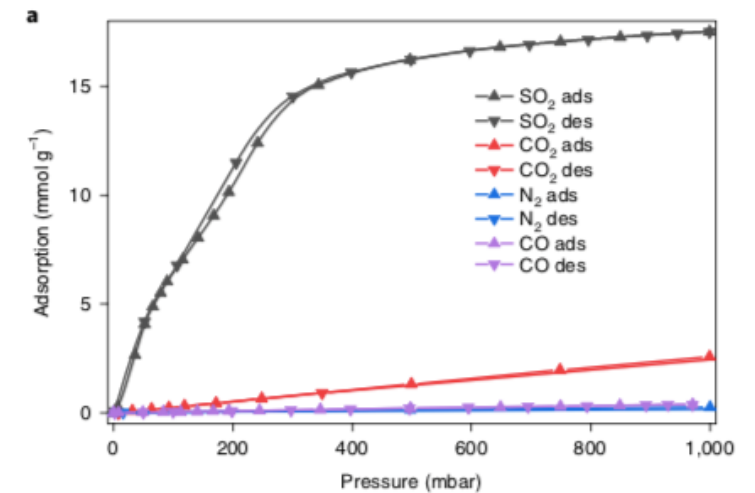
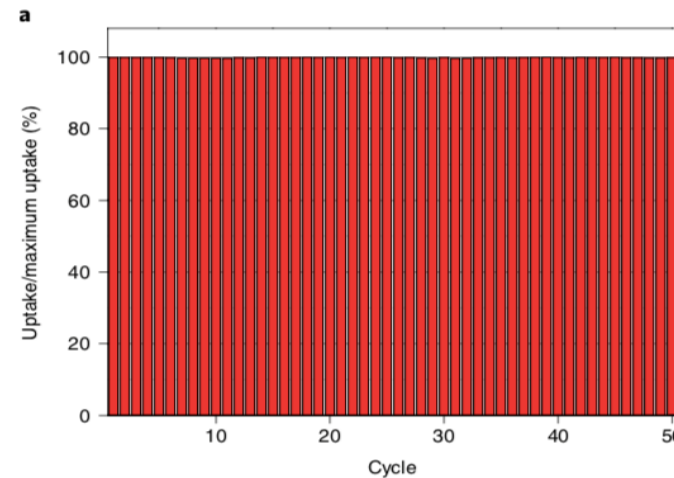
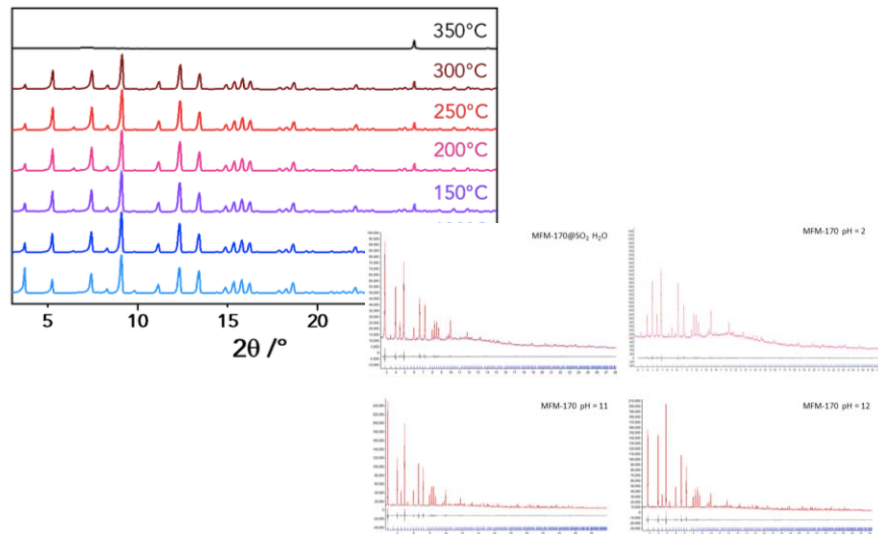
Stable towards heat, water and acidic and basic conditions : no loss of crystallinity or changes in the structure of the material. This is attributed to the unusual connectivity of the structure, where the axially coordinated pyridyl N-donors lock the two cubic lattices and block one of the two axial Cu(ii) sites.

- **High separation properties**

Reversible type I isotherm : MFM-170 can be fully regenerated under varying pressure conditions many times over
Efficient separation of SO₂ even in the presence of water and at elevated temperatures :

- **High selectivity**

At 1bar and 298K: MFM-170 shows an uptake of :
3.04mmol/g of CO₂
1.33mmol/g of CH₄
0.38mmol/g of CO
0.28mmol/g of N₂
(17,5 mmol/g of SO₂)

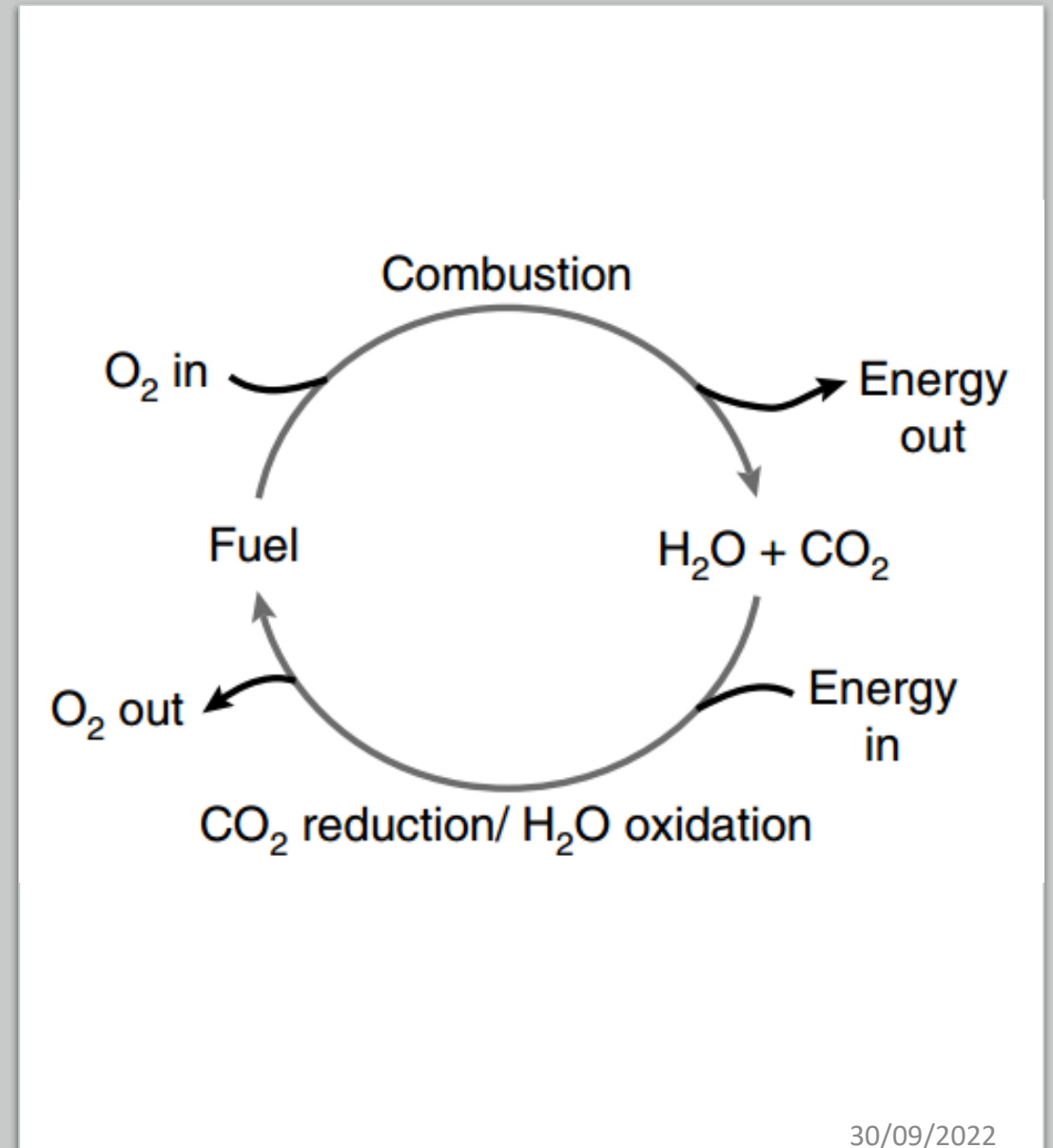


Bio-inspired hydrophobicity promotes CO₂ reduction on a Cu surface

Bio-inspired hydrophobicity promotes CO₂ reduction on a Cu surface

Hydrophobic Cu dendrite preparation and characterization

- Theorized sustainable energy cycle → relief to numerous environmental concerns and curtail dependency on fossil fuel
- Cycle driven through aqueous CO₂ electrolysis
- Cu = efficient and inexpensive catalyst for the CO₂ reduction
- Hydrophobic surfaces trap appreciable amount of gas
- Microscale and nanoscale surface structuration



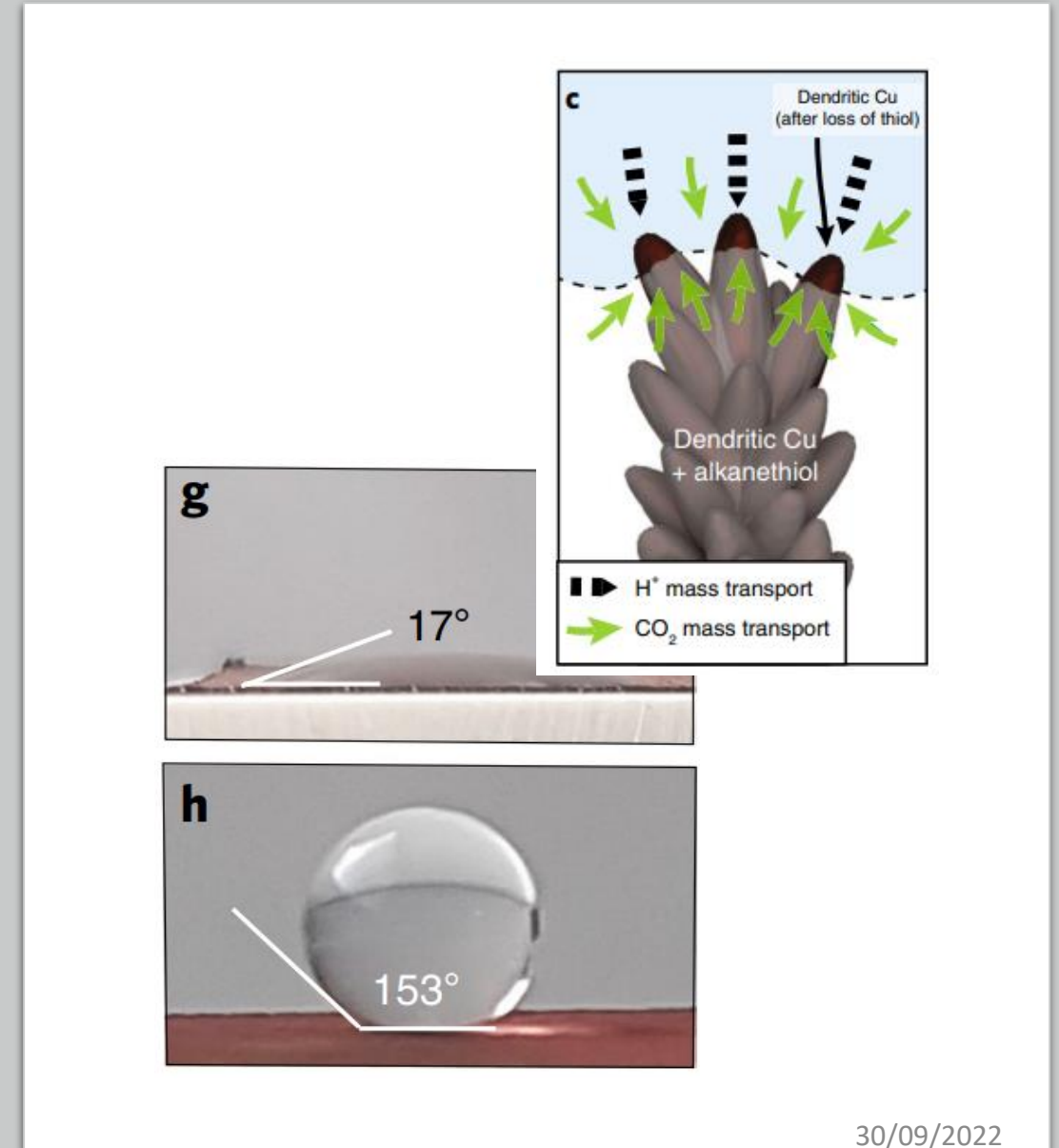
Bio-inspired hydrophobicity promotes CO₂ reduction on a Cu surface

Catalytic activity of hydrophobic and wettable Cu dendrites

- Hydrophobic treatment : submersing dendritic Cu into liquid 1-octadecanethiol
- Without treatment : surface hydrophilic
- Decrease in electrochemically active surface area (ECSA)
- Hydrophobic dendrite : 3,10-3 cm²
- Wettable dendrite : 21 cm²
- Gas trapping → decrease in ECSA

Conclusion

- Hydrophobic dendritic Cu → increase in the CO₂ reduction selectivity
- Gaseous layer trapped at the surface of the electrode
- Governing factor of CO₂ reduction selectivity on Cu



Thank you for your attention

Questions ?
